

Specification

LB580A

S	SC	Customer				
Drawn	Approval	Approval				

Rev. 02

December 2010



Contents

- 1. Features
- 2. Absolute Maximum Ratings
- 3. Electric-Optical Characteristics
- 4. Reliability Tests
- 5. Characteristic Diagrams
- 6. Color & Binning
- 7. Outline Dimensions
- 8. Standard of Taping Empty Space
- 9. Packing
- **10. Soldering**
- **11. Precaution for use**

Rev. 02

December 2010



LB580A

Description

Lamp LEDs are effective in hot thermal and humid condition. This high brightness and weather-resistant packaging design makes these Lamp LEDs ideal for Outdoor applications such as traffic signals, variable message signs and backlighting for transparent sign panels.



LB580A

Features

- High luminous
 emission
- Non-standoff leads
- 5mm type package
- Transparent
 epoxy lens
- Viewing angle : 80 °
- Dominant Wavelength
 :470nm

Applications

- Electronic signs and signals
- Specialty lighting
- Small area illumination
- Backlighting
- Other outdoor displays

Rev. 02 cember 2010

2. Absolute Maximum Ratings ($T_a = 25^{\circ}C$)									
Data	Item	Symbol	Value	Unit					
a S	DC Forward Current	I _F	30	mA					
he	Forward Peak Pulse Current	I _{FP} ^[1]	100	mA					
et	Reverse Voltage	V _R	5	V					
	Power Dissipation	P_D	114	mW					
	Operating Temperature	T _{opr}	-30 ~ 85	°C					
	Storage Temperature	T _{stg}	-40 ~ 100	°C					
	Solder Temperature	T _s	260°C for 10seconds ^[2]	٥C					

Notes :

[1] $t \le 0.1$ ms, D = 1/10

[2] No lower than 3mm from the base of the epoxy bulb.

3. Electro-Optical Characteristics ($T_a = 25^{\circ}C$, $I_F = 20mA$)

ltem	Symbol	Min.	Тур.	Max.	Unit	
Luminous Intensity ^[3]	/ _V ^[4]	-	250	380	mcd	
Dominant Wavelength ^[5]	λ_d	464	470	476	nm	
Forward Voltage [6]	V _F	-	3.6	3.8	V	
View Angle	$2 heta_{1/2}$		80		deg.	
Reverse Current (at $V_R = 5V$)	I _R	-	-	5	μA	

Notes :

[3] SSC maintains a tolerance of $\pm 10\%$ on intensity and power measurements.

[4] I_V is the luminous intensity output as measured with a cylinder.

[5] Dominant wavelength is derived from the CIE 1931 Chromaticity diagram.

A tolerance of ±0.5nm for dominant wavelength.

[6] A tolerance of ±0.05V on forward voltage measurements

서식번호: SSC-QP-7-07-24 (Rev.00)



4. Reliability Tests

אנינ		Item	Condition	Note	Failures		
DDD1		Life Test	$T_a = RT, I_F = 30mA$	1000hrs	0/22		
	н	igh Temperature Operating	$T_a = 85^{\circ}$ C, $I_F = 8$ mA	1000hrs	0/22		
	L	ow Temperature Operating	$T_a = -30^{\circ}$ C, $I_F = 20$ mA	1000hrs	0/22		
	-	Thermal Shock	Thermal Shock $T_a = -40^{\circ}C (30 \text{min}) \sim 100^{\circ} (30 \text{min})$ (Transfer time : 10sec, 1Cycle = 1hr)				
	R	esistance to soldering Heat	$T_s = 255 \pm 5^{\circ}$ C, $t = 10$ sec	1 time	0/22		
		ESD (Human Body Model)	1kV,1.5kΩ;100pF	1 time	0/22		
	ŀ	High Temperature Storage	<i>T_a</i> = 100°C	1000hrs	0/22		
		Low Temperature Storage	$T_a = -40^{\circ}{ m C}$	1000hrs	0/22		
		Temperature Humidity Storage	$T_a = 85^{\circ}$ C, $RH = 85\%$	1000hrs	0/22		
	Temperature Humidity Operating		$T_a = 85^{\circ}$ C, $RH = 85\%$, $I_F = 8$ mA	100hrs	0/22		

< Judging Criteria For Reliability Tests >

V _F	USL ^[1] X 1.2				
I _R	USL X 2.0				
$\phi_{_V}$	LSL ^[2] X 0.5				

Notes :

[1] USL : Upper Standard Level

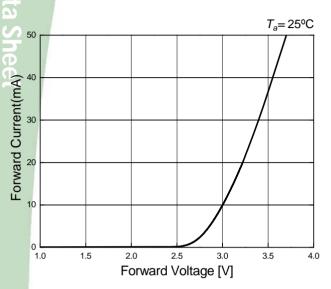
[2] LSL : Lower Standard Level.

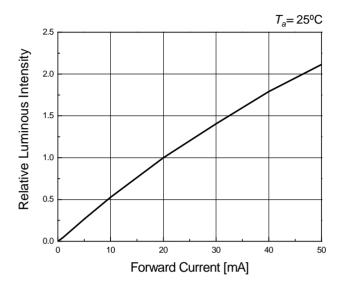
Rev. 02

December 2010



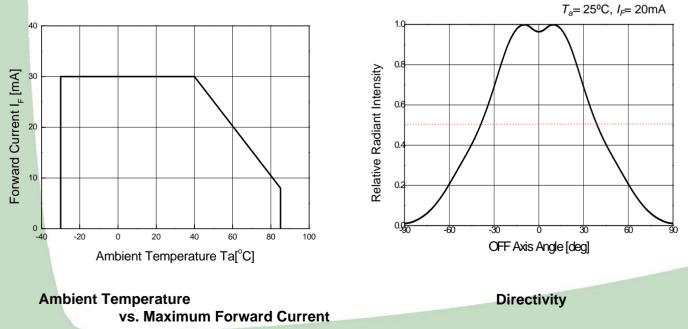






Forward Voltage vs. Forward Current

Forward Current vs. Relative Intensity



Rev. 02

December 2010



7

3.6

nical Data Sheet	6. Colo	r & Bin	ning									
Sh						Bin Code						
leet		Lumino Intensi					Forward Voltage		je			
	С		С		1		3					
					Ļ							
		ous Intensit D I _F =20m				Dominant Wavelength (nm) @ I _F =20mA				vard Voltag 2 I _F =20m	d Voltage (V) / _F =20mA	
	Bin Code	Min.	Max.		in ode	Min.	Ма	ax.	Bin Code	Min.	Max.	
	В	120	190		1	464	47	'0	3	2.8	3.0	
	С	190	270		2	470	47	'6	4	3.0	3.2	
	D	270	380						5	3.2	3.4	
									6	3.4	3.6	

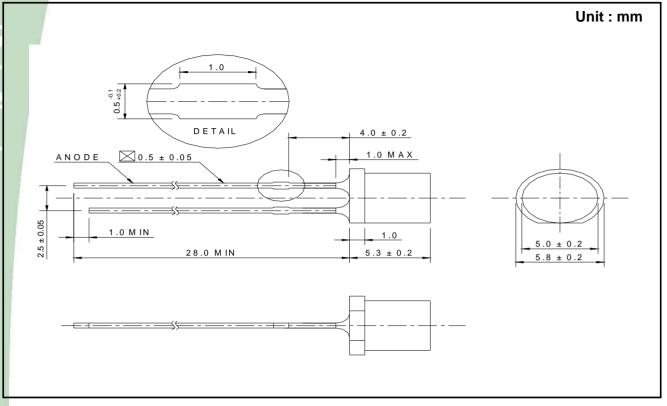
Available ranks

3.8

서식번호: SSC-QP-7-07-24 (Rev.00)

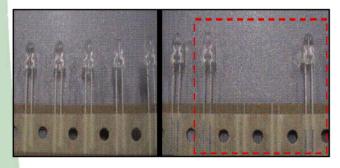


7. Outline Dimensions



Notes : Protruded epoxy is 1.0mm maximum.

8. Standard of Taping Empty Space



Available Empty Space : 2ea

Before

After

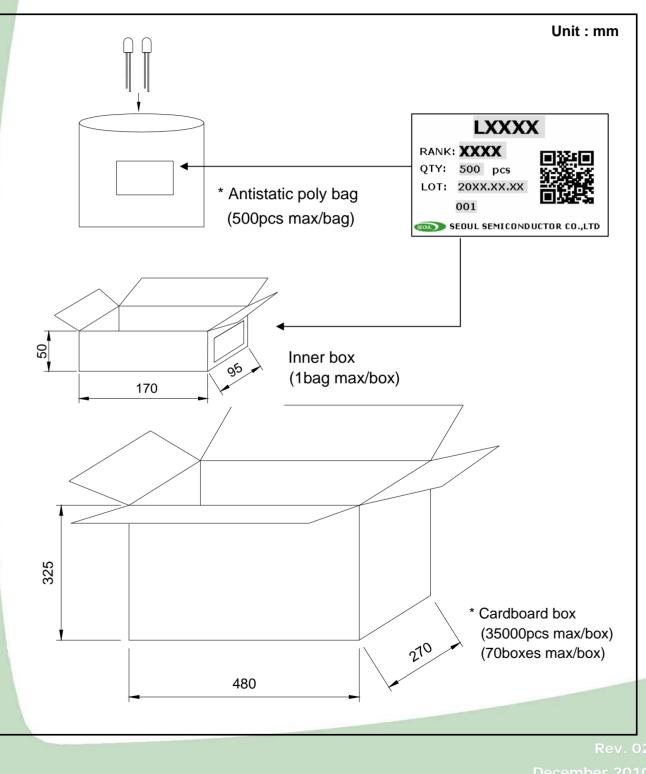
- * Purpose : Prevention of being Mixed & Reverse mounting
- * Before : Insert the right PKG after removing defective product
- * After : Attaching the right PKG on the backside after removing defective product

Rev. 02

December 2010





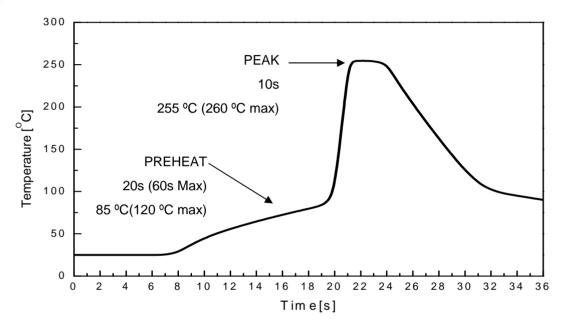


10. Soldering Profile

1) Wave Soldering Conditions / Profile

- Preliminary heating to be at 85°C(120 °C max) for 20 seconds(60 seconds max).
- Soldering heat to be at 255 °C (260°C max) for 10 seconds

• Soak time above 200 °C is 5 seconds



- 2) Hand Soldering conditions
- Not more than 3 seconds at max. 350°C, under Soldering iron.
- 3) Caution
- Lead frames are silver plated copper alloy. This substance has a low thermal coefficient (easily conducts heat)
- The LEDs must not be repositioned after soldering.
- Do not apply any stress to the lead particularly when heat.

Note : In case the soldered products are reused in soldering process, we don't guarantee the products.

Rev. 02

December 2010



SEOUL

11. Precaution for Use

- 1) Storage
- Before opening the package

Avoid the absorption of moisture, we recommended to store Lamp LEDs in a dry box(or desiccators) with a desiccant. Otherwise, store them in the following environment: Temperature : $5^{\circ}C \sim 30^{\circ}C$ Humidity : 50% max.

- After opening the package
 - a. Soldering should be done right after opening the package(within 24Hrs).
 - b. Keeping of a fraction
 - Sealing
 - Temperature : 5 ~ 40 $^\circ C$, Humidity : less than 30%
 - c. If the package has been opened more than 1week or the color of desiccant changes, Components should be dried for 10-12hr at $60\pm5^\circ$ C
- Any mechanical force or any excess vibration shall not be accepted to apply during cooling process to normal temp. after soldering.
- Avoid quick cooling
- Leadframes are silver plated SPCC. The silver plate surface may be affected by environments which contains corrosive substances. Please avoid conditions which may cause the LEDs to corrode, tarnish or discolor.
- 2) Lead Forming
 - When the lead forming is required before soldering, care must be taken to avoid any bending and mechanical stress. The stress to the base may damage the LEDs.
 - When mounting the LEDs onto a PCB, the holes on the circuit board should be exactly aligned with the leads of the LEDs.
 - It is recommended that tooling made to precisely form and cut the leads to length rather than rely on hand operating.

Rev. 02

December 2010

- 3) Static Electricity
- Static Electricity and surge voltage damage the LEDs. So it is recommended that a wrist band or an anti-electrostatic glove be used when handling the LEDs.
- All devices, equipment and machinery must be properly grounded.
 It is recommended precautions be taken against surge voltage to the equipment that mounts the LEDs.
- 4) Heat Generation
- Thermal is one of the important parameter to design the end product. Please consider the heat generation of the LEDs.
- The operating current should be decided after considering the ambient maximum temperature of LEDs.

5) Others

- The color of the LEDs is changed a little by an operating current and thermal.
- Anti radioactive ray design is not considered for the products listed here in.
- Gallium arsenide is used in some of the products listed in this publication. These products are dangerous if they are burned or smashed in the process of disposal. It is also dangerous to drink the liquid or inhale the gas generated by such products when chemically disposed.
- This device should not be used in any type of fluid such as water, oil, organic solvent and etc. When washing is required, IPA(Isopropyl Alcohol) should be used.
- When the LEDs are illuminating, operating current should be decided after considering the junction temperature.

Cf.) Please refer Ambient temperature vs. Forward Current graph on page 5

• The appearance and specifications of the product may be modified for improvement without notice.

SEOUL SEMICONDUCTOR CO., LTD. 148-29, Kasan-Dong, Keumchun-Gu, Seoul, Korea TEL : +82-2-3281-6269 FAX :+82-2-857-5430 www.seoulsemicon.com www.zled.com

Rev. 02

December 2010

SEOUL SEMICONDUCTOR

SEOUL